19-2645; Rev 0; 10/02

MAXIM

50Ω Dual SPST Analog Switches in UCSP

General Description

The MAX4731/MAX4732/MAX4733 low-voltage, dual, single-pole/single-throw (SPST) analog switches operate from a single +2V to +11V supply and handle Rail-to-Rail® analog signals. These switches exhibit low leakage current (0.1nA) and consume less than 0.5nW (typ) of quiescent power, making them ideal for battery-powered applications.

When powered from a +3V supply, these switches feature 50Ω (max) on-resistance (R_{ON}) with 3.5Ω (max) matching between channels, and 9Ω (max) flatness over the specified signal range.

The MAX4731 has two normally open (NO) switches, the MAX4732 has two normally closed (NC) switches, and the MAX4733 has one NO and one NC switch. The MAX4731/MAX4732/MAX4733 are available in a 9-bump chip-scale package (UCSP™) and an 8-pin µMAX package. The tiny UCSP occupies a 1.52mm × 1.52mm area and significantly reduces the required PC board area.

Applications

Battery-Powered Systems

Audio/Video-Signal Routing

Low-Voltage Data-Acquisition Systems

Cell Phones

Communications Circuits

PDAs

UCSP is a trademark of Maxim Integrated Products, Inc.
Rail-to-Rail is a registered trademark of Nippon Motorola, Ltd.

Features

- **1.52mm × 1.52mm UCSP Package**
- **Guaranteed On-Resistance (R_{ON})**
  25Ω (max) at +5V
  50Ω (max) at +3V
- **On-Resistance Matching**
  3Ω (max) at +5V
  3.5Ω (max) at +3V
- **Guaranteed <0.1nA Leakage Current at T_A = +25°C**
- **Single-Supply Operation from +2.0V to +11V**
- **TTL/CMOS-Logic Compatible**
- **-108dB Crosstalk (1MHz)**
- **-72dB Off-Isolation (1MHz)**
- **Low Power Consumption: 0.5nW (typ)**
- **Rail-to-Rail Signal Handling**

Ordering Information

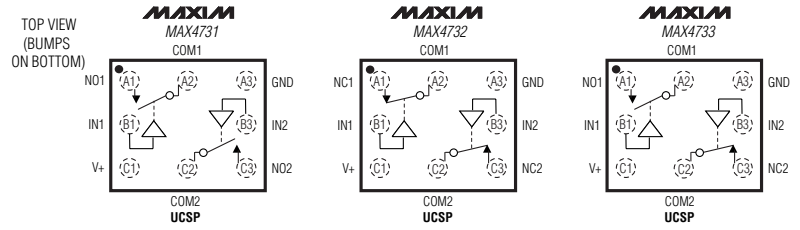
PART	TEMP RANGE	PIN/BUMP-PACKAGE	TOP MARK
MAX4731EUA	-40°C to +85°C	8 µMAX	—
MAX4731EBL-T*	-40°C to +85°C	9 UCSP-9**	ABV
MAX4732EUA	-40°C to +85°C	8 µMAX	—
MAX4732EBL-T*	-40°C to +85°C	9 UCSP-9**	ABT
MAX4733EUA	-40°C to +85°C	8 µMAX	—
MAX4733EBL-T*	-40°C to +85°C	9 UCSP-9**	ABS

Note: *Requires special solder temperature profile described in the Absolute Maximum Ratings section.*

**Future product—contact factory for availability.*

***UCSP reliability is integrally linked to the user's assembly methods, circuit board material, and environment. See the UCSP Reliability section of this data sheet for more information.*

Pin Configurations/Functional Diagrams/Truth Tables



MAX4731	
IN_	NO_
0	OFF
1	ON

SWITCHES SHOWN FOR LOGIC "0" INPUT

MAX4732	
IN_	NC_
0	ON
1	OFF

SWITCHES SHOWN FOR LOGIC "0" INPUT

MAX4733		
IN_	NO1	NC2
0	OFF	ON
1	ON	OFF

SWITCHES SHOWN FOR LOGIC "0" INPUT

Pin Configurations/Functional Diagrams/ Truth Tables continued at end of data sheet.

ABSOLUTE MAXIMUM RATINGS

(All Voltages Referenced to GND)
V+ .....-0.3V to +12V
IN_, COM_, NO_, NC_ (Note 1).....-0.3V to (V+ + 0.3V)
Continuous Current (any pin) .....±10mA
Peak Current (any pin, pulsed at 1ms, 10% duty cycle)...±20mA
Continuous Power Dissipation (T_A = +70°C)
8-Pin µMAX (derate 4.5mW/°C above +70°C) 362mW
9-Bump UCSP (derate 4.7mW/°C above +70°C).....379mW
Operating Temperature Range .....-40°C to +85°C
Storage Temperature Range .....-65°C to +150°C
Maximum Junction Temperature .....+150°C
Lead Temperature (soldering, 10s) .....+300°C
Bump Temperature (soldering, Note 2)
Infrared (15s) .....+220°C
Vapor Phase (60s) .....+215°C

Note 1: Signals on IN_, NO_, NC_, or COM_ exceeding V+ or GND are clamped by internal diodes. Limit forward-diode current to maximum current rating.

Note 2: This device is constructed using a unique set of packaging techniques that impose a limit on the thermal profile the device can be exposed to during board level solder attach and rework. This limit permits only the use of the solder profiles recommended in the industry-standard specification, JEDEC 020A, paragraph 7.6, Table 3 for IR/VPR and Convection reflow. Preheating is required. Hand or wave soldering is not allowed.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS—Single +3V Supply

(V+ = +3V ±10%, V_{IH} = +2.0V, V_{IL} = +0.8V, T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at V+ = +3V, T_A = +25°C.) (Notes 3, 4)

PARAMETER	SYMBOL	CONDITIONS	T_A	MIN	TYP	MAX	UNITS
ANALOG SWITCH							
Analog Signal Range	$V_{COM\_}$, $V_{NO\_}$, $V_{NC\_}$			0		V+	V
On-Resistance	R_{ON}	V+ = +2.7V, $I_{COM\_}$ = 5mA; $V_{NO\_}$ or $V_{NC\_}$ = +1.5V	+25°C		19	50	Ω
			T_{MIN} to T_{MAX}			60	
On-Resistance Matching Between Channels (Notes 5, 6)	ΔR_{ON}	V+ = +2.7V, $I_{COM\_}$ = 5mA; $V_{NO\_}$ or $V_{NC\_}$ = +1.5V	+25°C		0.8	3.5	Ω
			T_{MIN} to T_{MAX}			4.5	
On-Resistance Flatness (Note 7)	$R_{FLAT(ON)}$	V+ = +2.7V, $I_{COM\_}$ = 5mA; $V_{NO\_}$ or $V_{NC\_}$ = +1V, +1.5V, +2V	+25°C		2.3	9	Ω
			T_{MIN} to T_{MAX}			11	
NO_ or NC_ Off-Leakage Current (Note 8)	$I_{NO\_(OFF)}$ $I_{NC\_(OFF)}$	V+ = +3.6V, $V_{COM\_}$ = +0.3V, +3V; $V_{NO\_}$ or $V_{NC\_}$ = +3V, +0.3V	+25°C	-0.1		+0.1	nA
			T_{MIN} to T_{MAX}	-2		+2	
COM_ Off-Leakage Current (Note 8)	$I_{COM\_(OFF)}$	V+ = +3.6V, $V_{COM\_}$ = +0.3V, +3V; $V_{NO\_}$ or $V_{NC\_}$ = +3V, +0.3V	+25°C	-0.1		+0.1	nA
			T_{MIN} to T_{MAX}	-2		+2	
COM_ On-Leakage Current (Note 8)	$I_{COM\_(ON)}$	V+ = +3.6V, $V_{COM\_}$ = +0.3V, +3.0V; $V_{NO\_}$ or $V_{NC\_}$ = +0.3V, +3V, or floating	+25°C	-0.2		+0.2	nA
			T_{MIN} to T_{MAX}	-4		+4	

ELECTRICAL CHARACTERISTICS—Single +3V Supply (continued)

(V+ = +3V ±10%, V_{IH} = +2.0V, V_{IL} = +0.8V, T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at V+ = +3V, T_A = +25°C.) (Notes 3, 4)

PARAMETER	SYMBOL	CONDITIONS	T_A	MIN	TYP	MAX	UNITS
DYNAMIC CHARACTERISTICS							
Turn-On Time	t_{ON}	$V_{NO\_}$ or $V_{NC\_}$ = +1.5V, R_L = 300Ω, C_L = 35pF, Figure 2	+25°C		70	150	ns
			T_{MIN} to T_{MAX}			170	
Turn-Off Time	t_{OFF}	$V_{NO\_}$ or $V_{NC\_}$ = +1.5V, R_L = 300Ω, C_L = 35pF, Figure 2	+25°C		30	60	ns
			T_{MIN} to T_{MAX}			70	
Break-Before-Make (MAX4733 Only, Note 8)	t_{BBM}	$V_{NO\_}$ or $V_{NC\_}$ = +1.5V, R_L = 300Ω, C_L = 35pF, Figure 3	+25°C		40		ns
			T_{MIN} to T_{MAX}	1			
Charge Injection	Q	V_{GEN} = 0V, R_{GEN} = 0, C_L = 1.0nF, Figure 4	+25°C		7.5		pC
On-Channel -3dB Bandwidth	BW	Signal = 0dBm, 50Ω in and out	+25°C		300		MHz
Off-Isolation (Note 9)	V_{ISO}	f = 1MHz, $V_{COM\_}$ = $1V_{RMS}$, R_L = 50Ω, C_L = 5pF, Figure 5	+25°C		-72		dB
Crosstalk (Note 10)	V_{CT}	f = 1MHz, $V_{COM\_}$ = $1V_{RMS}$, R_L = 50Ω, C_L = 5pF, Figure 6	+25°C		-108		dB
NO_ or NC_ Off-Capacitance	C_{OFF}	f = 1MHz, Figure 7	+25°C		20		pF
COM_ Off-Capacitance	$C_{COM\_(OFF)}$	f = 1MHz, Figure 7	+25°C		20		pF
COM_ On-Capacitance	$C_{COM\_(ON)}$	f = 1MHz, Figure 7	+25°C		40		pF
LOGIC INPUT							
Input Logic High	V_{IH}			2.0			V
Input Logic Low	V_{IL}					0.8	V
Input Leakage Current	I_{IN}	$V_{IN\_}$ = 0V or V+		-1	+0.005	+1	µA
SUPPLY							
Power-Supply Range	V+			2.0		11	V
Positive Supply Current	I+	V+ = +5.5V, $V_{IN\_}$ = 0V or V+, all switches on or off			0.0001	1	µA

ELECTRICAL CHARACTERISTICS—Single +5V Supply

(V+ = +5V ±10%, V_{IH} = +2.0V, V_{IL} = +0.8V, T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at V+ = +5V, T_A = +25°C.) (Notes 3, 4)

PARAMETER	SYMBOL	CONDITIONS	T_A	MIN	TYP	MAX	UNITS
ANALOG SWITCH							
Analog Signal Range	$V_{COM\_}$, $V_{NO\_}$, $V_{NC\_}$			0		V+	V
On-Resistance	R_{ON}	V+ = +4.5V, $I_{COM\_}$ = 5mA, $V_{NO\_}$ or $V_{NC\_}$ = +3.5V	+25°C		8.5	25	Ω
			T_{MIN} to T_{MAX}			30	
On-Resistance Matching Between Channels (Notes 5, 6)	ΔR_{ON}	V+ = +4.5V, $I_{COM\_}$ = 5mA, $V_{NO\_}$ or $V_{NC\_}$ = +3.5V	+25°C		0.2	3	Ω
			T_{MIN} to T_{MAX}			4	
On-Resistance Flatness (Note 7)	$R_{FLAT(ON)}$	V+ = +4.5V, $I_{COM\_}$ = 5mA, $V_{NO\_}$ or $V_{NC\_}$ = +1V, +2V, +3V	+25°C		2	5	Ω
			T_{MIN} to T_{MAX}			7	
NO_ or NC_ Off-Leakage Current (Note 8)	$I_{NO\_(OFF)}$ $I_{NC\_(OFF)}$	V+ = +5.5V, $V_{COM\_}$ = +1V, +4.5V; $V_{NO\_}$ or $V_{NC\_}$ = +4.5V, +1V	+25°C	-0.1		+0.1	nA
			T_{MIN} to T_{MAX}	-2		+2	
COM_ Off-Leakage Current (Note 8)	$I_{COM\_(OFF)}$	V+ = +5.5V, $V_{COM\_}$ = +1V, +4.5V; $V_{NO\_}$ or $V_{NC\_}$ = +4.5V, +1V	+25°C	-0.1		+0.1	nA
			T_{MIN} to T_{MAX}	-2		+2	
COM_ On-Leakage Current (Note 8)	$I_{COM\_(ON)}$	V+ = +5.5V, $V_{COM\_}$ = +1V, +4.5V; $V_{NO\_}$ or $V_{NC\_}$ = +1V, +4.5V, or floating	+25°C	-0.2		+0.2	nA
			T_{MIN} to T_{MAX}	-4		+4	
DYNAMIC CHARACTERISTICS							
Turn-On Time	t_{ON}	$V_{NO\_}$ or $V_{NC\_}$ = +3.0V, R_L = 300Ω, C_L = 35pF, Figure 2	+25°C		47	85	ns
			T_{MIN} to T_{MAX}			95	
Turn-Off Time	t_{OFF}	$V_{NO\_}$ or $V_{NC\_}$ = +3.0V, R_L = 300Ω, C_L = 35pF, Figure 2	+25°C		23	45	ns
			T_{MIN} to T_{MAX}			55	
Break-Before-Make (MAX4733 Only, Note 8)	t_{BBM}	$V_{NO\_}$ or $V_{NC\_}$ = +3.0V, R_L = 300Ω, C_L = 35pF, Figure 3	+25°C		25		ns
			T_{MIN} to T_{MAX}	1			
Charge Injection	Q	V_{GEN} = 0V, R_{GEN} = 0, C_L = 1.0nF, Figure 4	+25°C		7.5		pC
On-Channel Bandwidth	BW	Signal = 0dBm, 50Ω in and out	+25°C		300		MHz
Off-Isolation (Note 9)	V_{ISO}	f = 1MHz, $V_{COM\_}$ = $1V_{RMS}$, R_L = 50Ω, C_L = 5pF, Figure 5	+25°C		-72		dB

ELECTRICAL CHARACTERISTICS—Single +5V Supply

(V+ = +5V ±10%, V_{IH} = +2.0V, V_{IL} = +0.8V, T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at V+ = +5V, T_A = +25°C.) (Notes 3, 4)

PARAMETER	SYMBOL	CONDITIONS	T_A	MIN	TYP	MAX	UNITS
Crosstalk (Note 10)	V_{CT}	f = 1MHz, $V_{COM\_}$ = $1V_{RMS}$, R_L = 50Ω, C_L = 5pF, Figure 6	+25°C		-108		dB
NO_ or NC_ Off-Capacitance	C_{OFF}	f = 1MHz, Figure 7	+25°C		20		pF
COM_ Off-Capacitance	$C_{COM\_(OFF)}$	f = 1MHz, Figure 7	+25°C		20		pF
COM_ On-Capacitance	$C_{COM\_(ON)}$	f = 1MHz, Figure 7	+25°C		40		pF
LOGIC INPUT							
Input Logic High	V_{IH}			2.0			V
Input Logic Low	V_{IL}					0.8	V
Input Leakage Current	I_{IN}	$V_{IN\_}$ = 0V or V+		-1	+0.005	+1	µA
SUPPLY							
Power-Supply Range	V+			2.0		11	V
Positive Supply Current	I+	V+ = +5.5V, $V_{IN\_}$ = 0V or V+, all switches on or off			0.0001	1	µA

Note 3: The algebraic convention, where the most negative value is a minimum and the most positive value a maximum, is used in this data sheet.

Note 4: UCSP parts are 100% tested at +25°C only, and guaranteed by design over temperature. µMAX parts are 100% tested at +85°C and +25°C and guaranteed by design over temperature.

Note 5: $\Delta R_{ON} = R_{ON(MAX)} - R_{ON(MIN)}$.

Note 6: UCSP on-resistance matching between channels and on-resistance flatness guaranteed by design.

Note 7: Flatness is defined as the difference between the maximum and minimum value of on-resistance as measured over the specified analog signal range.

Note 8: Guaranteed by design.

Note 9: Off-Isolation = $20 \log_{10} (V_{NO\_}/V_{COM\_})$, $V_{NO\_}$ = output, $V_{COM\_}$ = input to off switch.

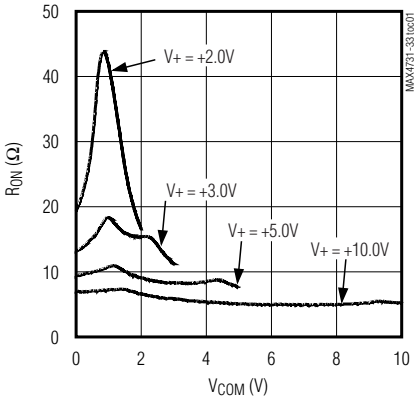
Note 10: Between any two switches.

50Ω Dual SPST Analog Switches in UCSP

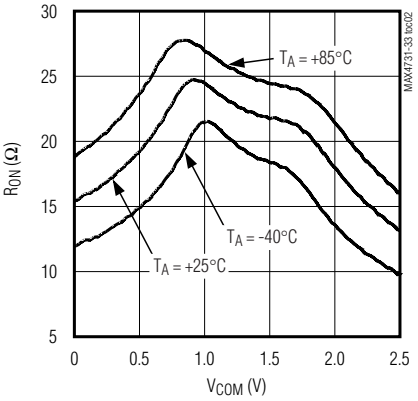
Typical Operating Characteristics

(T_A = +25°C, unless otherwise noted.)

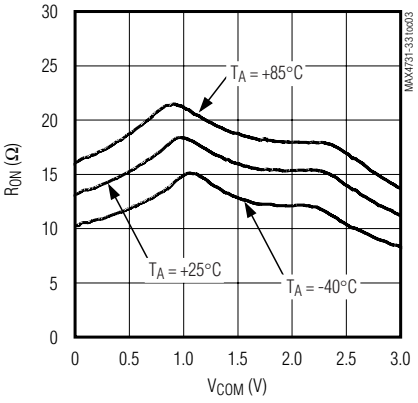
ON-RESISTANCE vs. V_{COM}



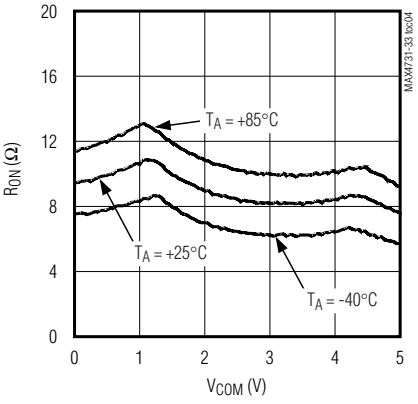
ON-RESISTANCE vs. V_{COM} (V+ = +2.5V)



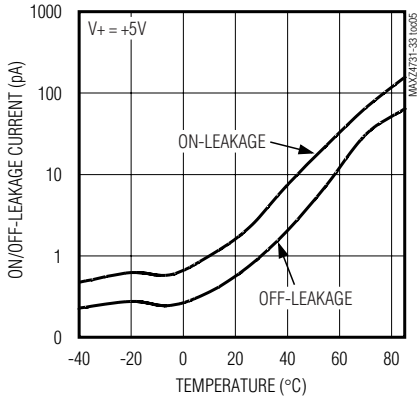
ON-RESISTANCE vs. V_{COM} (V+ = +3.0V)



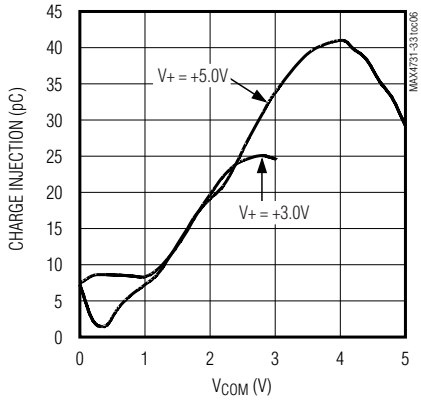
ON-RESISTANCE vs. V_{COM} (V+ = +5.0V)



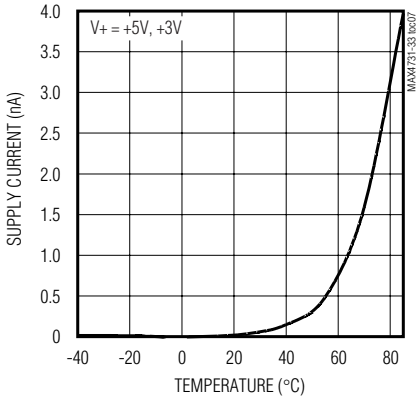
ON/OFF-LEAKAGE CURRENT vs. TEMPERATURE



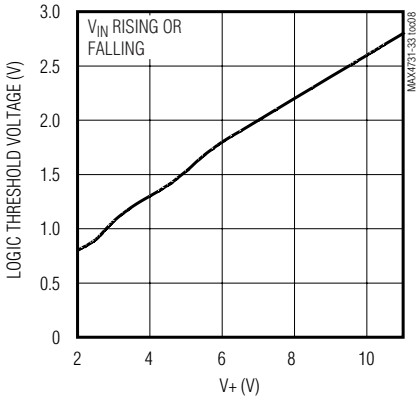
CHARGE INJECTION vs. V_{COM}



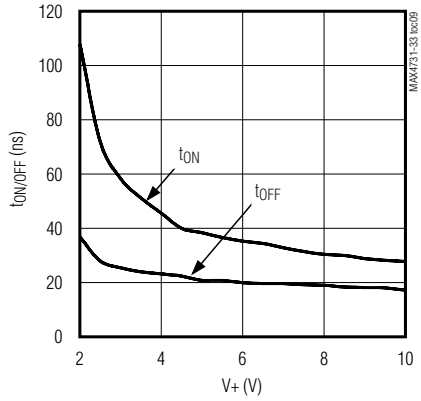
SUPPLY CURRENT vs. TEMPERATURE



LOGIC THRESHOLD VOLTAGE vs. SUPPLY VOLTAGE



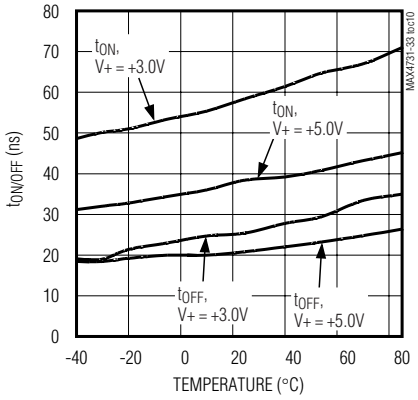
TURN-ON/OFF TIME vs. SUPPLY VOLTAGE



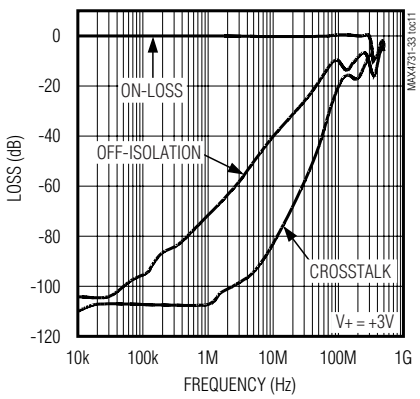
Typical Operating Characteristics (continued)

(T_A = +25°C, unless otherwise noted.)

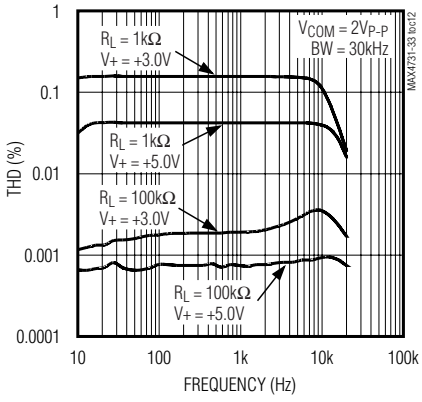
TURN-ON/OFF TIME vs. TEMPERATURE



FREQUENCY RESPONSE



TOTAL HARMONIC DISTORTION vs. FREQUENCY



Pin Description

PIN						NAME	FUNCTION
MAX4731		MAX4732		MAX4733			
UCSP	µMAX	UCSP	µMAX	UCSP	µMAX		
A1	1	—	—	A1	1	NO1	Analog-Switch Normally Open Terminal
A2	2	A2	2	A2	2	COM1	Analog-Switch Common Terminal
A3	4	A3	4	A3	4	GND	Ground. Connect to digital ground.
B1	7	B1	7	B1	7	IN1	Logic-Control Digital Input
B3	3	B3	3	B3	3	IN2	Logic-Control Digital Input
C1	8	C1	8	C1	8	V+	Positive Supply Voltage Input
C2	6	C2	6	C2	6	COM2	Analog-Switch Common Terminal
C3	5	—	—	—	—	NO2	Analog-Switch Normally Open Terminal
—	—	A1	1	—	—	NC1	Analog-Switch Normally Closed Terminal
—	—	C3	5	C3	5	NC2	Analog-Switch Normally Closed Terminal

Applications Information

Operating Considerations for High-Voltage Supply

The MAX4731/MAX4732/MAX4733 operate to +11V with some precautions. The absolute maximum rating for V+ is +12V (referenced to GND). When operating near this region, bypass V+ with a minimum 0.1µF capacitor to ground as close to the IC as possible.

Logic Levels

The MAX4731/MAX4732/MAX4733 are TTL compatible when powered from a single +5V supply. When powered from other supply voltages, the logic inputs should be driven rail-to-rail. For example, with a +11V supply, IN1 and IN2 should be driven low to 0V and high to 11V. With a +3.3V supply, IN1 and IN2 should be driven low to 0V and high to 3.3V. Driving IN1 and IN2 rail-to-rail minimizes power consumption.

Analog Signal Levels

Analog signals that range over the entire supply voltage (GND to V+) pass with very little change in R_{ON} (see *Typical Operating Characteristics*). The bidirectional switches allow NO_, NC_, and COM_ connections to be used as either inputs or outputs.

Power-Supply Sequencing and Overvoltage Protection

CAUTION: Do not exceed the absolute maximum ratings. Stresses beyond the listed ratings can cause permanent damage to the devices.

Proper power-supply sequencing is recommended for all CMOS devices. Always apply V+ before applying analog signals, especially if the analog signal is not current limited. If this sequencing is not possible, and if the analog inputs are not current limited to <20mA, add a small-signal diode, D1, as shown in Figure 1. If the analog signal can dip below GND, add D2. Adding protection diodes reduces the analog signal range to a diode drop (about 0.7V) below V+ (for D1), and to a diode drop above ground (for D2). Leakage is unaffected by adding the diodes. On-resistance increases slightly at low supply voltages. Maximum supply voltage (V+) must not exceed +11V.

Adding protection diodes causes the logic thresholds to be shifted relative to the power-supply rails. The most significant shift occurs when using low supply voltages (+5V or less). With a +5V supply, TTL compatibility is not guaranteed when protection diodes are added. Driving IN1 and IN2 all the way to the supply rails (i.e., to a diode drop higher than the V+ pin, or to a diode drop lower than the GND pin) is always acceptable.

Protection diodes D1 and D2 also protect against some overvoltage situations. Using the circuit in Figure 1, no damage results if the supply voltage is below the absolute maximum rating (+12V) and if a fault voltage up to the absolute maximum rating (V+ + 0.3V) is applied to an analog signal terminal.

UCSP Package Consideration

For general UCSP package information and PC layout considerations, please refer to the Maxim Application Note, “Wafer-Level Chip-Scale Packages.”

UCSP Reliability

The chip-scale package (UCSP) represents a unique package that greatly reduces board space compared to other packages. UCSP reliability is integrally linked to the user’s assembly methods, circuit board material, and usage environment. The user should closely review these areas when considering a UCSP. Performance through Operation Life Test and Moisture Resistance is equal to conventional package technology as the wafer-fabrication process primarily determines it. However, this form factor may not perform equally to a packaged product through traditional mechanical reliability tests.

Mechanical stress performance is a greater consideration for a UCSP. UCSP solder joint contact integrity must be considered since the package is attached through direct solder contact to the user’s PC board. Testing done to characterize the UCSP reliability performance shows that it is capable of performing reliably through environmental stresses. Results of environmental stress test and additional usage data and recommendations are detailed in the UCSP application note, which can be found on Maxim’s website at www.maxim-ic.com.

Test Circuits/Timing Diagrams

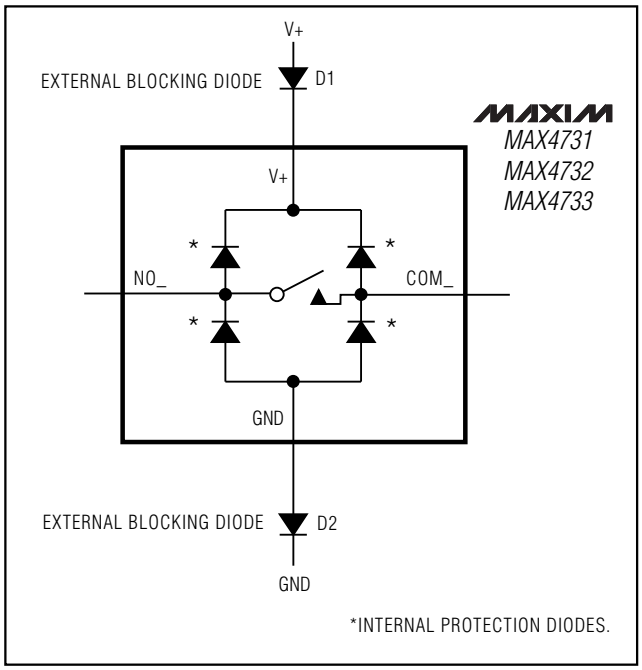


Figure 1. Overvoltage Protection Using External Blocking Diodes

Test Circuits/Timing Diagrams (continued)

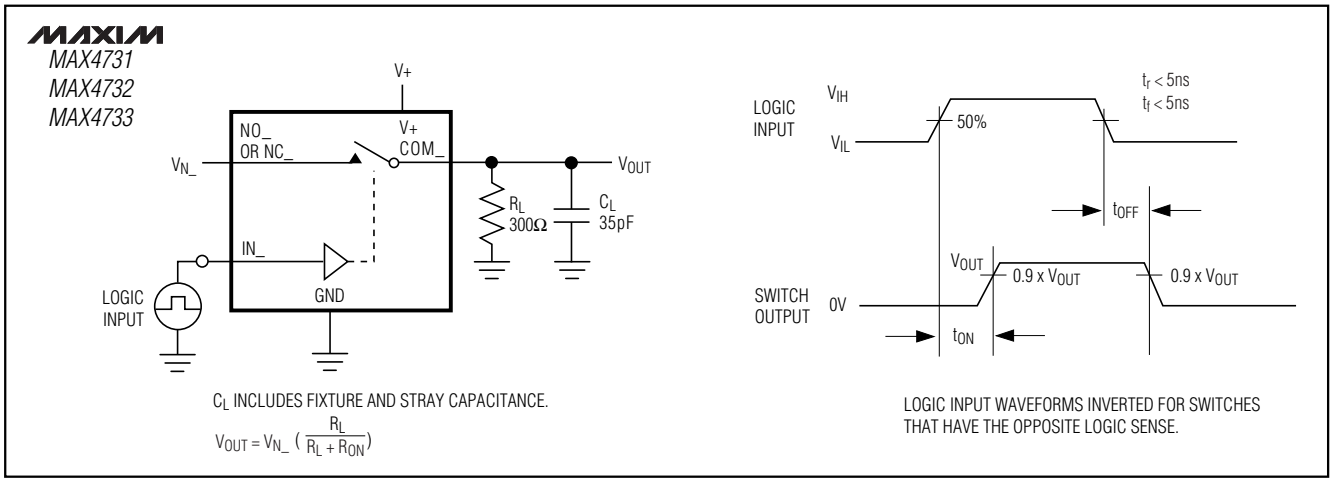


Figure 2. Switching Time

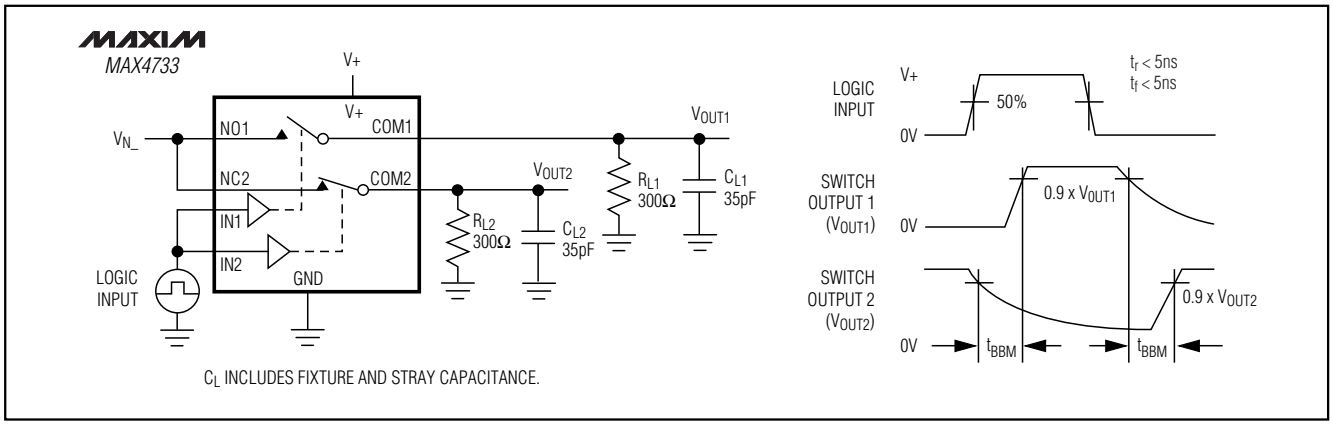


Figure 3. Break-Before-Make Interval (MAX4733 only)

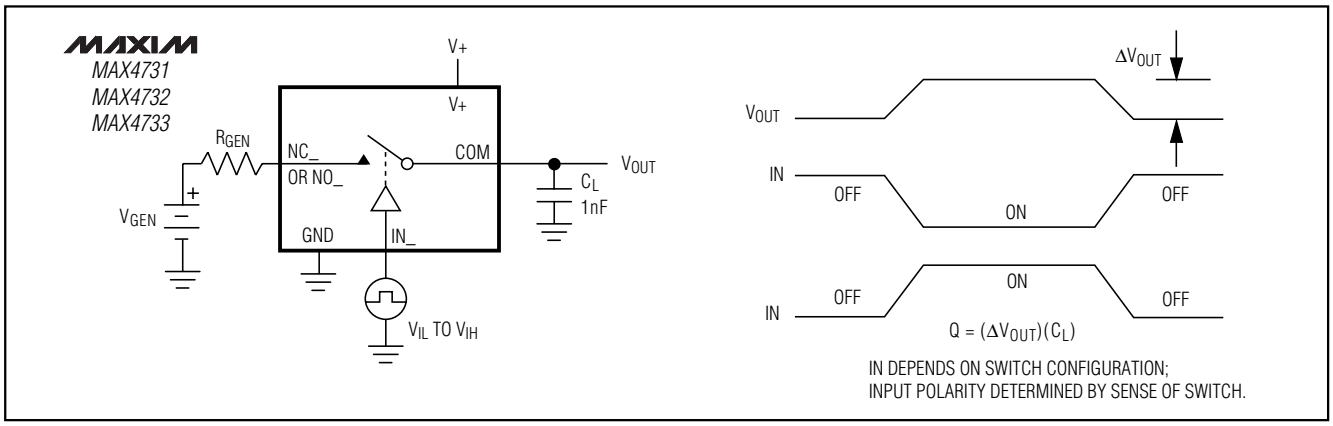


Figure 4. Charge Injection

50Ω Dual SPST Analog Switches in UCSP

Test Circuits/Timing Diagrams (continued)

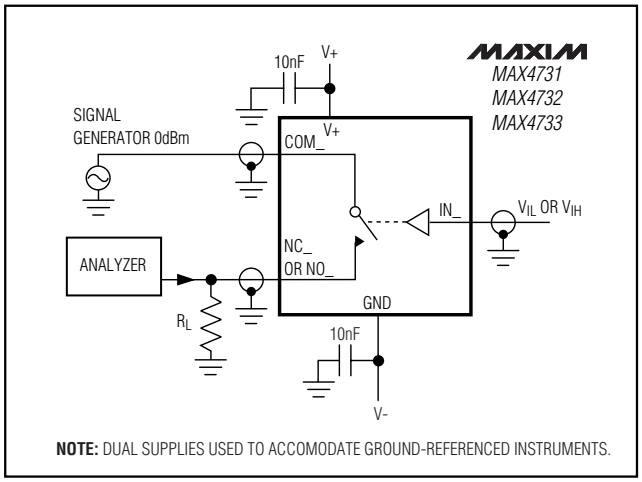


Figure 5. Off-Isolation/On-Channel Bandwidth

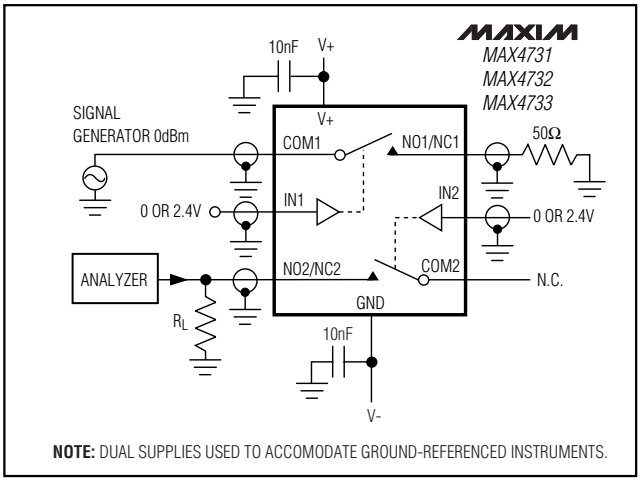


Figure 6. Crosstalk

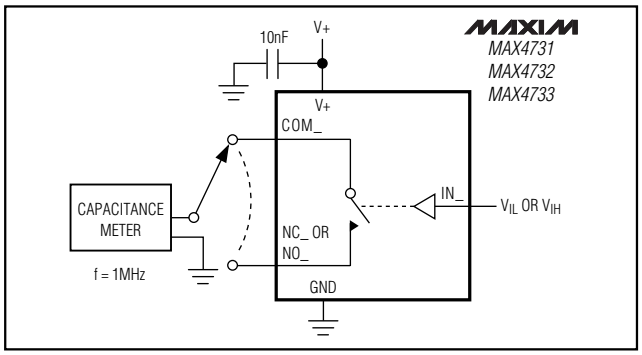


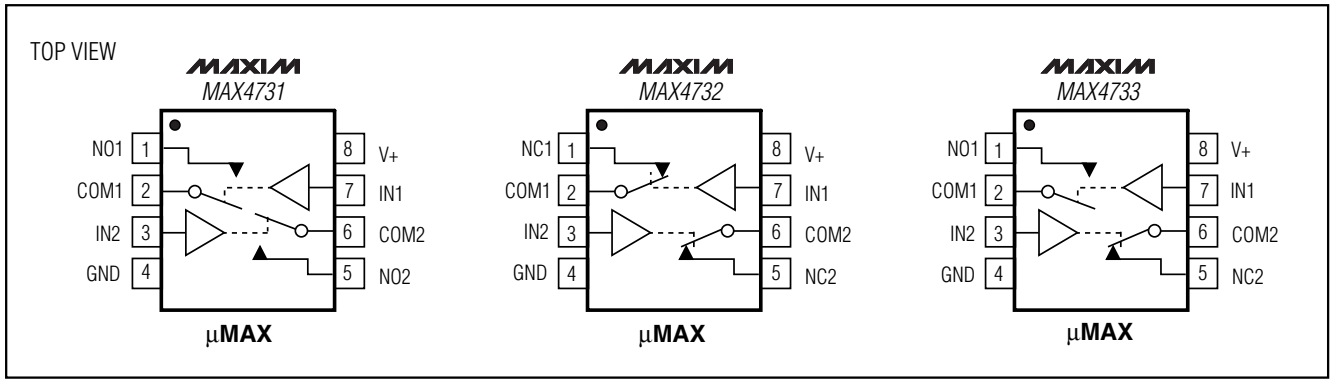
Figure 7. Channel Off/On-Capacitance

Chip Information

TRANSITOR COUNT: 68

PROCESS: CMOS

Pin Configurations/Functional Diagrams/Truth Tables (continued)

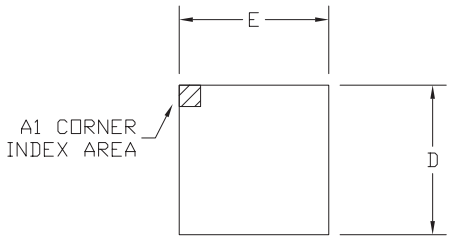


Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)

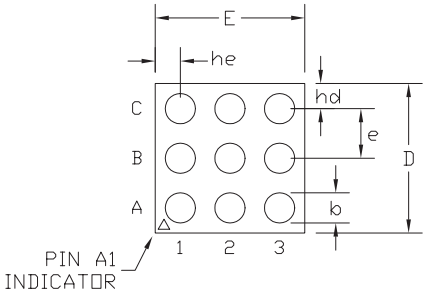
SYMBOL	DIMENSIONS
A	0.60±0.05
D	1.52±0.05
E	1.52±0.05
e	0.50 BASIC
b	ø 0.35 BASIC
A1	0.27±0.04
A2	0.33 Ref.
hd	0.26 Ref.
he	0.26 Ref.

SOLDER BALL DEPOPULATION	
PKG. CODE	DEPOPULATED BALL
B9-1	NONE
B9-2	B2
B9-3	B1, B2, B3

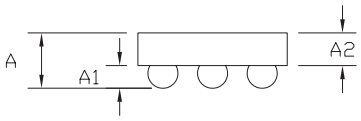


TOP VIEW

NOTES:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. MEETS JEDEC M0195.



BOTTOM VIEW



SIDE VIEW

MAXIM
PROPRIETARY INFORMATION

TITLE:
PACKAGE OUTLINE, 3x3 UCSP

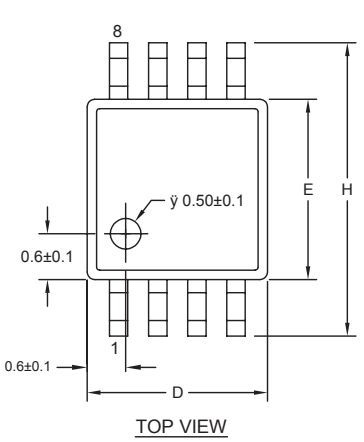
APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-0093	E	1/1

50Ω Dual SPST Analog Switches in UCSP

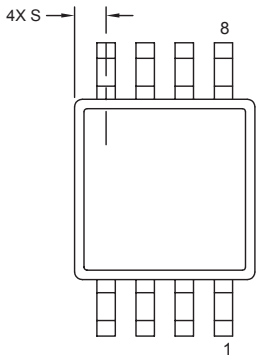
Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)

8LUMAXD.EPS

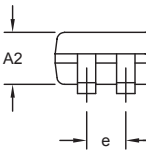


TOP VIEW

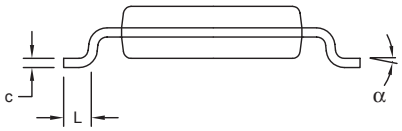


BOTTOM VIEW

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	-	0.043	-	1.10
A1	0.002	0.006	0.05	0.15
A2	0.030	0.037	0.75	0.95
b	0.010	0.014	0.25	0.36
c	0.005	0.007	0.13	0.18
D	0.116	0.120	2.95	3.05
e	0.0256 BSC		0.65 BSC	
E	0.116	0.120	2.95	3.05
H	0.188	0.198	4.78	5.03
L	0.016	0.026	0.41	0.66
α	0∞	6∞	0∞	6∞
S	0.0207 BSC		0.5250 BSC	



FRONT VIEW



SIDE VIEW

NOTES:
1. D&E DO NOT INCLUDE MOLD FLASH.
2. MOLD FLASH OR PROTRUSIONS NOT TO EXCEED 0.15MM (.006").
3. CONTROLLING DIMENSION: MILLIMETERS.
4. MEETS JEDEC MO-187C-AA.

DALLAS SEMICONDUCTOR MAXIM

PROPRIETARY INFORMATION

TITLE: PACKAGE OUTLINE, 8L uMAX/uSOP

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-0036	J	1/1